

Docket No. \_\_\_\_\_

**COMBINED DECLARATION/POWER OF ATTORNEY**  
**FOR PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

LEADFRAME, PLASTIC-ENCAPSULATED SEMICONDUCTOR DEVICE, AND  
METHOD FOR FABRICATING THE SAME, the specification of which

(check one)        X   is attached hereto.

\_\_\_\_\_ was filed on \_\_\_\_\_ as  
 Application Serial No. \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed
<u>2002-309320</u> (Number)	<u>JAPAN</u> (Country)	<u>24/10/2002</u> (Day/Month/Year Filed)	<u>  X  </u> Yes <u>  </u> No
<u>2002-309324</u> (Number)	<u>JAPAN</u> (Country)	<u>24/10/2002</u> (Day/Month/Year Filed)	<u>  X  </u> Yes <u>  </u> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<u>  </u> Yes <u>  </u> No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Appln. Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)
(Appln. Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)

I hereby appoint as my attorneys, with full power of substitution and revocation, to prosecute the patent application identified above and to transact all business in the U.S. Patent and Trademark Office connected therewith: Raphael V. Lupo (Reg. No. 28,363); Jack Q. Lever, Jr. (Reg. No. 28,149); Kenneth L. Cage (Reg. No. 26,151); Stanislaus Aksman (Reg. No. 28,562); Paul Devinsky (Reg. No. 28,553); Edward E. Kubasiewicz (Reg. No. 30,020), Michael E. Fogarty (Reg. No. 36,139); Brian E. Ferguson (Reg. No. 36,801); Robert W. Zelnick (Reg. No. 36,976); and Wilhlem F. Gadiano (Reg. No. 37,136).

Please address all correspondence and telephone calls to:

Jack Q. Lever, Jr.  
McDERMOTT, WILL & EMERY  
600 Thirteenth Street, N.W.  
Washington, D.C. 20005-3096  
(202) 756-8000

The undersigned hereby authorizes the U.S. attorneys named herein to accept and follow instructions from Maeda Patent Office as to any action to be taken in the Patent and Trademark Office regarding this application without direct communication between the U.S. attorney and the undersigned. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by the undersigned.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Masanori MINAMIO  
Inventor's signature Masanori Minamio Date October 20, 2003  
Residence\* Osaka, Japan Citizenship Japan  
Post Office Address 2-10-7, Utsukushigaoka, Takatsuki-shi, Osaka 569-1111, Japan

Full name of second inventor Hiroshi HORIKI

Inventor's signature Hiroshi Horiki Date October 20, 2003

Residence\* Kyoto, Japan Citizenship Japan

Post Office Address 5-33-202, Yokota, Sonobe-cho, Funai-gun, Kyoto 622-0051, Japan

Full name of third inventor Tetsushi NISHIO

Inventor's signature Tetsushi Nishio Date October 20, 2003

Residence\* Kyoto, Japan Citizenship Japan

Post Office Address 1-10-205, Noshō-shimono, Fushimi-ku, Kyoto-shi, Kyoto 612-8267, Japan

\* City and State, or City and Country for foreign inventors

Docket No.: 60188-686

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
	:	
Masanori MINAMIO, et al.	:	Confirmation Number:
	:	
Serial No.:	:	Group Art Unit:
	:	
Filed: October 22, 2003	:	Examiner:
	:	
For:		LEADFRAME, PLASTIC-ENCAPSULATED SEMICONDUCTOR DEVICE, AND METHOD FOR FABRICATING THE SAME

**ASSOCIATE POWER OF ATTORNEY**

Mail Stop  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The undersigned Principal Attorney of record hereby appoints the following Attorneys as his Associates with regard to the above-identified application: Steven W. Allis, Reg. No. 50,532; Stephen A. Becker, Reg. No. 26,527; John G. Bisbikis, Reg. No. 37,095; Daniel Bucca, Reg. No. 42,368; Kenneth L. Cage, Reg. No. 26,151; Jennifer Chen, Reg. No. 42,404; Bernard P. Codd, Reg. No. 46,429; Lawrence T. Cullen, Reg. No. 44,489; Paul Devinsky, Reg. No. 28,553; Margaret M. Duncan, Reg. No. 30,879; Shamita De. Etienne-Cummings, Reg. No. 46,072; Ramyar M. Farid, Reg. No. 46,692; Brian E. Ferguson, Reg. No. 36,801; Michael E. Fogarty, Reg. No. 36,139; John R. Fuisz, Reg. No. 37,327; Keith E. George, Reg. No. 34,111; John A. Hankins, Reg. No. 32,029; Eric J. Kraus, Reg. No. 36,190; Catherine Krupka, Reg. No. 46,227; Jack Q. Lever, Reg. No. 28,149; Raphael V. Lupo, Reg. No. 28,363; Michael A. Messina, Reg. No. 33,424; Dawn L. Palmer, Reg. No. 41,238; Joseph H. Paquin, Jr., Reg. No. 31,647; Scott D. Paul, Reg. No. 42,984; William D. Pegg, Reg. No. 42,988; Robert L. Price, Reg. No. 22,685; Gene Z. Robinson, Reg. No. 33,351; Brian K. Seidleck, Reg. No. 51,321; Joy Ann G. Serauskas, Reg. No. 27,952; Jiri F. Smetana, Reg. No. 52,456; David A. Spenard, Reg. No. 37,449; Arthur J. Steiner, Reg. No. 26,106; Michael D. Switzer, Reg. No. 39,552; David M. Tennant, Reg. No. 48,362; Judith L. Toffenetti, Reg. No. 39,048; Daniel S. Trainor, Reg. No. 43,959; Shival P. Virmani, Reg. No.

**Serial No.:**

45,032; Kelli N. Watson, Reg. No. 47,170; Cameron K. Weiffenbach, Reg. No. 44,488; Aaron Weisstuch, Reg. No. 41,557; Edward J. Wise, Reg. No. 34,523; Jeffrey A. Woller, Reg. No. 48,041; Alexander V. Yampolsky, Reg. No. 36,324; Robert W. Zelnick, Reg. No. 36,976; and Wei-Chen Chen, admitted under 37 CFR 10.9(b) all of

McDERMOTT, WILL & EMERY  
600 13th Street, N.W.  
Washington, DC 20005-3096

Please continue to address all communications to the undersigned.

October 22, 2003

By 

\_\_\_\_\_  
Michael E. Fogarty  
Registration No. 36,139  
Attorney for Applicant